



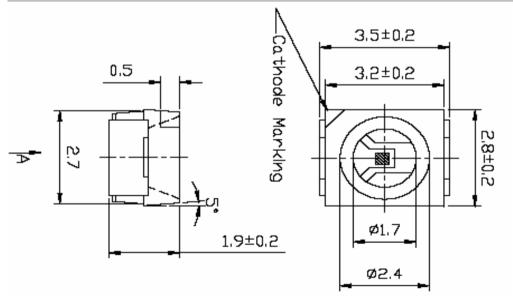
The Power of LED Light

### Typical Electrical & Optical Characteristics (IF=350mA and Ta=25°C)

Part-No.	Waveler or CCT	inant ngth (nm) (K) X / Y rod.		l Voltage √)		ous Flux acd)	Cur- rent (mA)	50% Power Angle
	Min	Max.	Min	Max	Min	Тур	max	Тур
M11A1317	625	630	2,3	2,6	8179	12000	50	120

- 1. Tolerance of measurement of luminous flux: +/-15% 2. Tolerance of measurement of dominant Wavelength: +/-1nm
- 3. Tolerance of measurement of CCT ( Correlated color temperature +/- 200K
- 4. Tolerance of measurement of forward voltage +/-0,1V

### **Technical Dimensions**









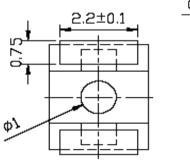
### **Features**

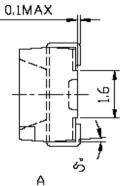
Contour Lights Garden Lighting **Genral Lighting** Reading Lights

### Absulut Maximum Ratings (Ta=25°C)

Items	Symb ols	Absulut maximum Rating	Unit
	OIS	Red	
Power Dissipation	Pd	850	mW
Forward Current	If	350	mA
Peak Forward Current	lfp	500	Ма
LED Junction Temperature	Tj	125	°C
Operating Temperature	Topr	30°C ~ +110°C	°C
Storage Temperature	Tstg	40°C ~ +120°C	°C

<sup>\*</sup> Pulse width ≤ 0,1msec duty ≤ 1/10







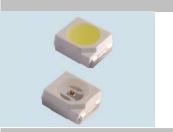
### SMD DIAMOND TOP-**LED**

Part No.: M11A1317

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.07.2010	Custo
from 10	Cusio

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010	
APPD:	Schumi			FINISH	Jamy		Shee	t No.	1 from 10	ľ











### The Power of LED Light

### **BIN GUIDE / HIGH POWER**

Tolerance of measurement of luminous Flux is +/- 15%

Code	Luminous	Flux Range	Code	Luminous Flux Range				
Code	min	max.	Code	min	max.			
Α	1	2	P2	70	80			
В	2	2,5	M1	80	90			
С	2,5	3,2	M2	90	100			
D	3,2	4	N1	100	110			
Е	4	5	N2	110	120			
F	5	6,2	P1	120	130			
G	6,2	7,7	P2	130	140			
Н	7,7	9,6	Q1	140	150			
J	9,6	12		150	160			
K	12	15	R1	160	170			
L1	15	19	R2	170	180			
L2	19	24	S1	180	200			
M1	24	30	S2	200	220			
M2	30	40	T1	220	240			
N1	40	50	T2	240	260			
N2	50	60	U1	250	280			
P1	60	70						
		В	+	G/E	F			

Code	CCT	Range	Code	CCT Range			
Code	Min	Max	Code	Min	Max		
А	2700	2900	M	4900	5100		
В	2900	3100	N	5100	5500		
С	3100	3300	Р	5500	6000		
D	3300	3500	Q	6000	6500		
E	3500	3700	R	6500	7000		
F	3700	3900	S	7000	7500		
G	3900	4100	T	7500	8000		
Н	4100	4300	U	8000	9000		
J	4300	4500	V	9000	10000		
K	4500	4700	W	10000	12000		
L	4700	4900					

Tolerance of measurement of CCT is +/-100K.

FI	JO		U												_
		3		1	G	G/E		F	,	Y	C	/P	R	/U	
Color Code	Min	max	Min	max	Min	max	Min	max	Min	max	Min	max	Min	max	ent of +/-1nm
D0	450	455	490	495	515	520	560	565	580	583	600	605	620	625	ent
D1	455	460	495	500	520	525	565	570	583	586	605	610	625	630	rem i.
D2	460	465	500	505	525	530	570	575	586	589	610	615	630	635	Tolerance of measurem
D3	465	470	505	510	530	535	575	580	589	592	615	620	635	640	ne d
D4	470	475	510	515	535	540			592	595			640	645	o of
D5	475	480			540	545			595	598			645	650	Tolerance
D6	480	485			545	550							650	655	lera
D7	485	490			550	555							655	660	) L
D8					555	560							660	665	
DRW:	Jas	son	CH	IKD	Wil	lson	MA	TL:	Wilson		TOLERANCE		Mason		
APPD:	Sch	numi					FIN	IISH	Ja	my			Sheet N		t No.

DATE

SMD DIAMOND TOP-**LED** 

Part No.: M11A1317

Customer:

12.07.2010

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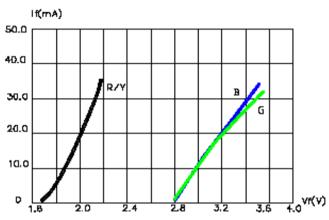






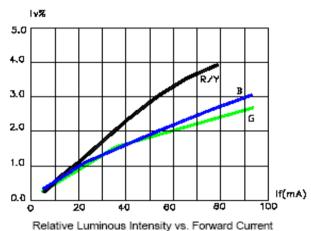


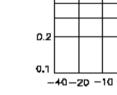
Typical Electrical / Optical Characteristics Curves (Ta=25°C Unless otherwise noted)

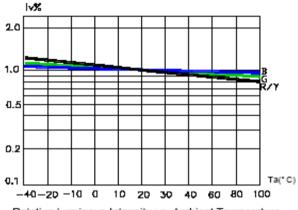


Forward Current vs. Forward Voltage









Relative Luminous Intensity vs. Ambient Temperature

1.0	<b>√%</b>																		
1.4			В	П	l	П	G	1	١			Y	N	R	Λ		П		
8.0				I	L			ı	١				I		I				
				П	Т	Т		П	П	Г		Г	П	П	П	l	Τ	$\neg$	
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0.4			1	$\perp$	1	$\perp$	1			ļ		Ц		М	$\perp$	1	$\perp$	╛	
			И		4		l			۱		V		1		١			
0.2			L	4	4	Ц	L			4		L		A	4	_	$\perp$	╝	
		١.	,			V				١	/	ĺ		Λ	l		U		
0.0				_	_	4		,		_	×	_			Ч	_		_	WL(nm)
40			50				JO			55			Ġ(				350		
	Relative Luminous Intensity vs. Wavelength																		

Code	Forward Vo	oltage Rank
Code	Min.	Max.
Α	1,6	1,8
В	1,8	2,0
С	2,0	2,2
D	2,2	2,4
E	2,4	2,6
F	2,6	2,8
G	2,8	3,0
Н	3,0	3,2

Tolerance of measurement of forward voltage is +/-0,1\
--

Code	Forward Vo	oltage Rank			
Code	Min.	Max.			
J	3,20	3,40			
K	3,40	3,60			
L	3,60	3,80			
М	3,80	4,00			
N	4,00	4,20			
Р	4,20	4,40			
Q	4,40	4,60			
R	4,60	4,80			

SMD DIAMOND	TOP-
LED	

12.07.2010	Customer:
3 from 10	Customer.

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010	$\int_{C}$
APPD:	Schumi			FINISH	Jamy		Shee	t No.	3 from 10	ľ



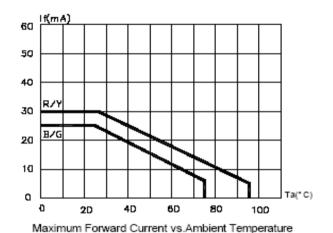


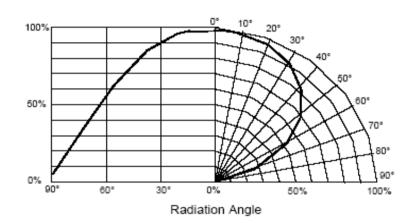






# Typical Representative Spatial Radiation Paddern of single LED

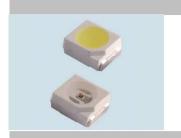




# Recommended Solder Pad 1.5 1.5 1.5 3 Solder resist

SMD DIAM	/IOND	TOP-				
LED						
Part No.:	M11A	1317				

DRW: CHKD Wilson MATL: Wilson **TOLERANCE** Mason 12.07.2010 Jason DATE Customer: APPD: FINISH 4 from 10 Schumi Sheet No. Jamy









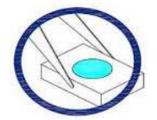


# **Handling Informations**

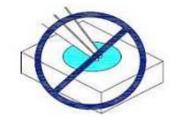
- 4. The outer diameter of the TOP LED pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although ist characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of th LED.

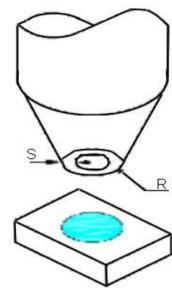
1. Handle the component along the side surfaces by using forceps or appropriate tools







2. Do not directly touch or handle the silicone lens surfance. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratsch the silicone lens or damage the internal circuitry.

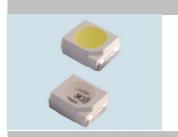


SMD DIAMOND	TOP-
LED	

Part No.: **M11A1317** 

Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010
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### **Moisture Proof Packing**

In Order to prevent moisture absorption into DIAMOND = TOP LED / XEON POWER during the transportation and storage. DIAMOND TOP-LED / XEON-POWER LED is packed in a moisture barrier bag. Desiccants and humidity indicator are packed together with DIAMOND TOP-LED / XEON-POWER LED as the secondary protection. The indication of humidity card provides the information of humidity within TOP Packing.

### Storage

Shelf life in original sealed bag in storage condition of <40°C and 90% RH is 12 mounths. Baking is required whenever shelf life is expired. Before opening the packaging please check wether bag leak air or not. After opening the DIAMOND TOP-LED / XEON POWER LED must be storad under the condition <30°C and 60% RH. Under this condition DIAMOND TOP-LED / XEON POWER LED must be used (subject to reflow) within 24-hours after bag opening, and re-baking is required when exceeding 24 hours. For baking, place DIAMOND TOP-LED / XEON POWER LED in oven at temperature 75°C +/-5°C and relative humidity <10%RH, for 24 hours. Take out the material from packaging bag for re-bake. Do not open the door of oven frequently during the baking process.

Manual soldering (We do not recommend this method strongly).

No mechanical stress should be exerted on the resin portion of DIAMOND TOP-LED / XEON POWER during soldering.

Handling of DIAMOND TOP-LED / XEON POWER LED should be done when the package has been cooled down to below 40°C or less. This is to prevent the DIAMOND TOP-LED / XEON POWER failures due the thermal-mechanical strss during handling.

Reflow soldering should not be done more than one time.

No stress should be exerted on the package during soldering.

Electrostatic Discharge and Surge current.

Electrostatic discharge (ESD) or surge current (EOS) may damage LED.

Precautions such as ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling DIAMOND TOP-LED / XEON POWER LED.

All devices, equipment and machinery must be prpertly grounded.

It is recommended to perform electrical test to screen out ESD failures in final inspection.

It is important to eliminate the possibility of surge current during circuity design.

### Heat Management

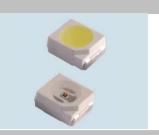
Heat manegement of DIAMOND TOP-LED / XEON POWER must be taken into into consideration during the design stage of DIAMOND TOP-LED / XEON POWER LED application. The current should be de-rated appropriately by refering to the de-rating curve attached on each product specification.

SMD DIAMOND TOP-LED

Part No.: M11A1317

DRW: CHKD Wilson MATL: Wilson **TOLERANCE** Mason 12.07.2010 Jason DATE APPD: Schumi **FINISH** Sheet No. 6 from 10 Jamy

email: info@edcon-components.com



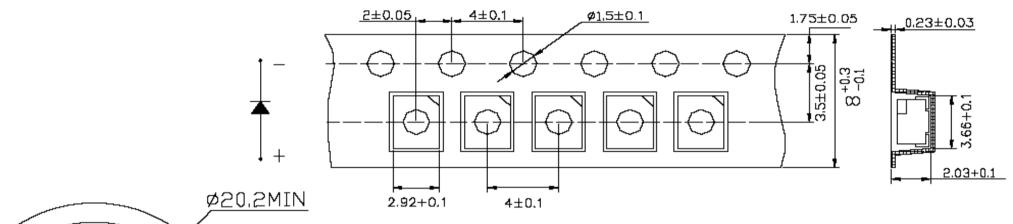


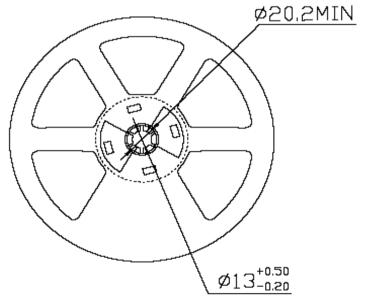


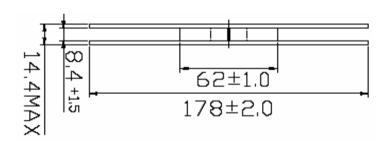




# **Packing Specifications**



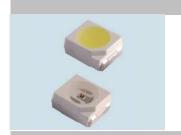




SMD DIAMOND	TOP-
LED	

Part No.: **M11A1317** 

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010
APPD:	Schumi			FINISH	Jamy		Shee	t No.	7 from 10











# **Ordering Informations**

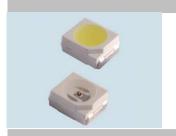
Serie	Color Code	ROHS	Packing				
						,	
M11A1317	RD	R	TR				

<b>DD</b> Dod	<b>R</b> = ROHS	TR= TAPE	
RD= Red	Conform	REEL	
	N= NON	<b>BU</b> = Bulk-	
	ROHS	Ware	

SMD DIAMOND TOP-LED

Part No.: **M11A1317** 

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010
APPD:	Schumi			FINISH	Jamy		Shee	et No.	8 from 10





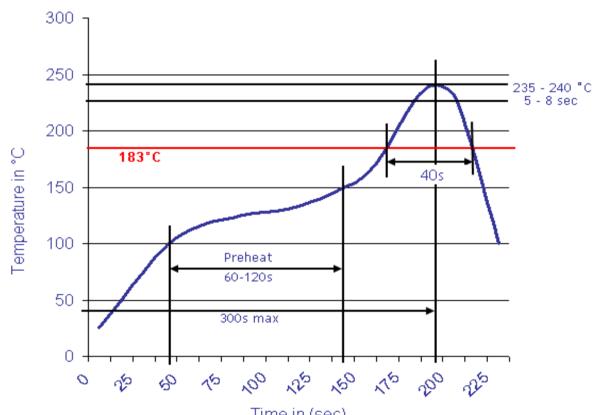






# **Soldering Profile Curve**

# Classification Reflow Profile (JEDEC J-STD-020C)

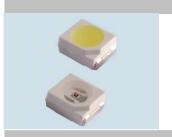


Time in (sec)

DRW: CHKD Wilson MATL: Wilson **TOLERANCE** Mason DATE 12.07.2010 Jason APPD: FINISH Schumi Sheet No. 9 from 10 Jamy

SMD DIAMOND TOP-**LED** 

Part No.: M11A1317



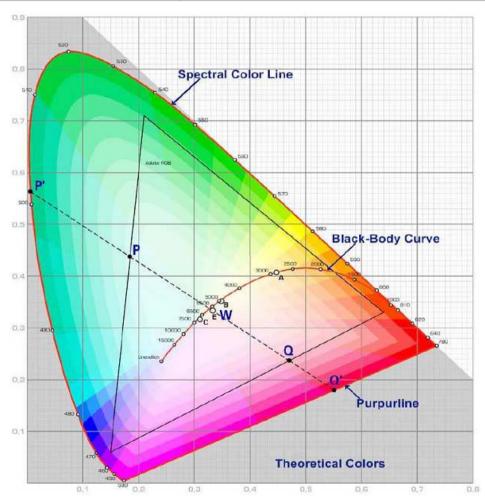








# **Spectral Color Curve**



SMD DIAMOND	TOP-
LED	

Part No.: **M11A1317** 

Customer:

CHKD DRW: Wilson MATL: Jason Wilson TOLERANCE Mason DATE 12.07.2010 APPD: FINISH Schumi Sheet No. 10 from 10 Jamy